Renesas Electronics America Inc - M30878FJAGP#U3 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, EBI/EMI, I²C, IEBus, IrDA, SIO, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	121
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 34x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LFQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30878fjagp-u3

Table 1.3 Specifications (100-Pin Package) (1/2)

Item	Function	Specification
CPU	Central processing unit	M32C/80 core (multiplier: 16 bits × 16 bits → 32 bits multiply-addition operation instructions: 16 × 16 + 48 → 48 bits) • Basic instructions: 108 • Minimum instruction execution time: 31.3 ns (f(CPU) = 32 MHz, VCC1 = 4.2 to 5.5 V) 41.7 ns (f(CPU) = 24 MHz, VCC1 = 3.0 to 5.5 V) • Operating mode: Single-chip mode, memory expansion mode, and microprocessor mode
Memory	ROM, RAM, data flash	See **Tables 1.5 to 1.7 Product List**.
Power Supply Voltage Detection		Vdet3 detection function, Vdet4 detection function, cold start/warm start determination function
External Bus Expansion	Bus/memory expansion function	• Address space: 16 Mbytes • External bus interface: 1 to 7 wait states can be inserted, 4 chip select outputs, 3 V and 5 V interfaces • Bus format: Switchable between separate bus and multiplexed bus formats, switchable data bus width (8-bit or 16-bit)
Clock	Clock generation circuits	• 4 circuits: Main clock, sub clock, on-chip oscillator, PLL frequency synthesizer • Oscillation stop detection: Main clock oscillation stop detection function • Frequency divider circuit: Dividing ratio selectable among 1, 2, 3, 4, 6, 8, 10, 12, 14, 16 • Low power consumption features: Wait mode, stop mode
Interrupts		• Interrupt vectors: 70 • External interrupt inputs: 11 ($\overline{\text{NMI}}$, $\overline{\text{INT}}$ × 6, key input × 4) • Interrupt priority levels: 7
Watchdog Timer		15-bit × 1 channel (with prescaler)
DMA	DMAC	• 4 channels, cycle steal method • Trigger sources: 43 • Transfer modes: 2 (single transfer and repeat transfer)
	DMACII	• Can be activated by all peripheral function interrupt sources • Transfer modes: 2 (single transfer and burst transfer) • Immediate transfer, calculation transfer, and chain transfer functions
Timer	Timer A	16-bit timer × 5 Timer mode, event counter mode, one-shot timer mode, pulse width modulation (PWM) mode, Event counter 2-phase pulse signal processing (2-phase encoder input) × 3
	Timer B	16-bit timer × 6 Timer mode, event counter mode, pulse period measurement mode, pulse width measurement mode
	Timer function for 3-phase motor control	3-phase inverter control × 1 (using timer A1, timer A2, timer A4, and timer B2) On-chip dead time timer

Table 1.4 Specifications (100-Pin Package) (2/2)

Item	Function	Specification
Serial Interface	UART0 to UART4	Clock synchronous/asynchronous × 5 I^2C bus, special mode 2, GCI mode, SIM mode, IrDA mode(2), IEBus (optional)(1)(3)
	UART5	Clock synchronous/asynchronous × 1
A/D Converter		10-bit resolution × 26 channels (in single-chip mode) 10-bit resolution × 10 channels (in memory expansion mode and microprocessor mode) Including sample and hold function
D/A Converter		8-bit resolution × 2 channels
CRC Calculation Circuit		CRC-CCITT ($X^{16} + X^{12} + X^5 + 1$) compliant
X/Y Converter		16 bits x 16 bits
Intelligent I/O		16-bit timer × 2 • Time measurement function (input capture): 8 channels • Waveform generation function (output compare): 10 channels • Communication function: Clock synchronous mode, clock asynchronous mode, HDLC data processing mode, IEBus (optional)(1)(3) • 2-phase pulse signal processing (2-phase encoder input) × 1
ROM Correction Function		Address match interrupt × 8
CAN modules		Supporting CAN 2.0B specification M32C/87: 16 slots × 2 channels, M32C/87A: 16 slots × 1 channel M32C/87B: none
I/O Ports	Programmable I/O ports	• Input only: 1 • CMOS I/O: 85, selectable pull-up resistor • N channel open drain ports: 2
Flash Memory		• Erase and program voltage: 3.3 V ± 0.3 V or 5.0 V ± 0.5 V • Erase and program endurance: 100 times (all areas) • Program security: ROM code protect and ID code check • Debug functions: On-chip debug and on-board flash reprogram
Operating Frequency/Supply Voltage		32 MHz: VCC1 = 4.2 to 5.5 V, VCC2 = 3.0 V to VCC1 24 MHz: VCC1 = 3.0 to 5.5 V, VCC2 = 3.0 V to VCC1
Current Consumption		32 mA (32 MHz, VCC1 = VCC2 = 5 V) 23 mA (24 MHz, VCC1 = VCC2 = 3.3 V) 45 μA (approx. 1 MHz, VCC1 = VCC2 = 3.3 V, on-chip oscillator low-power consumption mode → wait mode) 0.8 μA (VCC1 = VCC2 = 3.3 V, stop mode)
Operating Ambient Temperature (°C)		-20 to 85°C, -40 to 85°C (optional)(3)
Package		100-pin LQFP (PLQP0100KB-A) 100-pin QFP (PRQP0100JB-A)

NOTES:
1. IEBus is a registered trademark of NEC Electronics Corporation.
2. Available in UART0.
3. Please contact a Renesas sales office for optional features.

1.2 Product List

Tables 1.5 to 1.7 list product information. Figure 1.1 shows product numbering system.

Table 1.5 M32C/87 Group (1) (M32C/87: 2-channel CAN module) Current as of Jul. 2008

Part Number	Package Code	ROM Capacity	RAM Capacity	Remarks
M3087BFLGP	PLQP0144KA-A (144P6Q-A)	1 MB + 4 KB(1)	48 KB	Flash memory
M30879FLFP	PRQP0100JB-A (100P6S-A)			
M30879FLGP	PLQP0100KB-A (100P6Q-A)			
M3087BFKGP	PLQP0144KA-A (144P6Q-A)	768 KB + 4 KB(1)		
M30879FKGP	PLQP0100KB-A (100P6Q-A)			
M30878FJGP	PLQP0144KA-A (144P6Q-A)	512 KB + 4 KB(1)	31 KB	
M30876FJGP	PLQP0100KB-A (100P6Q-A)			
M30875FHGP	PLQP0144KA-A (144P6Q-A)	384 KB + 4 KB(1)	24 KB	
M30873FHGP	PLQP0100KB-A (100P6Q-A)			
M30878MJ-XXXGP	PLQP0144KA-A (144P6Q-A)	512 KB	31 KB	Mask ROM
M30876MJ-XXXFP	PRQP0100JB-A (100P6S-A)			
M30876MJ-XXXGP	PLQP0100KB-A (100P6Q-A)			
M30875MH-XXXGP	PLQP0144KA-A (144P6Q-A)	384 KB	24 KB	
M30873MH-XXXGP	PLQP0100KB-A (100P6Q-A)			

NOTE:
1. Additional 4-Kbyte space is available for data flash memory.

Table 1.6 M32C/87 Group (2) (M32C/87A: 1-channel CAN module) Current as of Jul. 2008

Part Number	Package Code	ROM Capacity	RAM Capacity	Remarks
M3087BFLAGP	PLQP0144KA-A (144P6Q-A)	1 MB + 4 KB(1)	48 KB	Flash memory
M30879FLAFP	PRQP0100JB-A (100P6S-A)			
M30879FLAGP	PLQP0100KB-A (100P6Q-A)			
M3087BFKAGP	PLQP0144KA-A (144P6Q-A)	768 KB + 4 KB(1)		
M30879FKAGP	PLQP0100KB-A (100P6Q-A)			
M30878FJAGP	PLQP0144KA-A (144P6Q-A)	512 KB + 4 KB(1)	31 KB	
M30876FJAGP	PLQP0100KB-A (100P6Q-A)			
M30875FHAGP	PLQP0144KA-A (144P6Q-A)	384 KB + 4 KB(1)	24 KB	
M30873FHAGP	PLQP0100KB-A (100P6Q-A)			
M30878MJA-XXXGP	PLQP0144KA-A (144P6Q-A)	512 KB	31 KB	Mask ROM
M30876MJA-XXXFP	PRQP0100JB-A (100P6S-A)			
M30876MJA-XXXGP	PLQP0100KB-A (100P6Q-A)			
M30875MHA-XXXGP	PLQP0144KA-A (144P6Q-A)	384 KB	24 KB	
M30873MHA-XXXGP	PLQP0100KB-A (100P6Q-A)			

NOTE:
1. Additional 4-Kbyte space is available for data flash memory.

Table 1.9 144-Pin Package List of Pin Names (2/4)

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin	Intelligent I/O Pin	Analog Pin	Bus Control Pin
41	VSS							
42		P6_5			CLK1			
43		P6_4			$\overline{\text{CTS1}}$/$\overline{\text{RTS1}}$/$\overline{\text{SS1}}$	OUTC2_1/ISCLK2		
44		P6_3			TXD0/SDA0/SRXD0/ IrDAOUT			
45		P6_2			RXD0/SCL0/STXD0/ IrDAIN			
46		P6_1		RTP0_1	CLK0			
47		P6_0		RTP0_0	$\overline{\text{CTS0}}$/$\overline{\text{RTS0}}$/$\overline{\text{SS0}}$			
48		P13_7				OUTC2_7		
49		P13_6				OUTC2_1/ISCLK2		
50		P13_5				OUTC2_2/ISRXD2/ IEIN		
51		P13_4				OUTC2_0/ISTXD2/ IEOUT		
52		P5_7						$\overline{\text{RDY}}$
53		P5_6						ALE
54		P5_5						$\overline{\text{HOLD}}$
55		P5_4						$\overline{\text{HLDA}}$/ALE
56		P13_3				OUTC2_3		
57	VSS							
58		P13_2				OUTC2_6		
59	VCC2							
60		P13_1				OUTC2_5		
61		P13_0				OUTC2_4		
62	CLKOUT	P5_3						BCLK/ALE
63		P5_2						$\overline{\text{RD}}$
64		P5_1						$\overline{\text{WRH}}$/$\overline{\text{BHE}}$
65		P5_0						$\overline{\text{WRL}}$/$\overline{\text{WR}}$
66		P12_7						
67		P12_6						
68		P12_5						
69		P4_7						$\overline{\text{CS0}}$/A23
70		P4_6						$\overline{\text{CS1}}$/A22
71		P4_5						$\overline{\text{CS2}}$/A21
72		P4_4						$\overline{\text{CS3}}$/A20
73		P4_3						A19
74	VCC2							
75		P4_2						A18
76	VSS							
77		P4_1						A17
78		P4_0						A16
79		P3_7						A15,[A15/D15]
80		P3_6						A14,[A14/D14]

Table 1.17 Pin Functions (100-Pin and 144-Pin Package) (3/4)

Type	Symbol	I/O Type	Supply Voltage	Description
Intelligent I/O	INPC1_0 to INPC1_3	I	VCC1/ VCC2(1)	Input pins for the time measurement function.
	INPC1_4 to INPC1_7	I	VCC1	
	OUTC1_0 to OUTC1_3	O	VCC1/ VCC2(1)	Output pins for the waveform generation function. (OUTC1_6/OUTC2_0 and OUTC1_7/OUTC2_2 assigned to ports 7_0 and 7_1 are N-channel open drain output.)
	OUTC1_4 to OUTC1_7	O	VCC1	
	OUTC2_0 to OUTC2_2	O	VCC1/ VCC2(1)	
	ISCLK0	I/O	VCC1	Clock input/output pins for the intelligent I/O communication function.
	ISCLK1, ISCLK2	I/O	VCC1/ VCC2(1)	
	ISRXD0	I	VCC1	Data input pins for the intelligent I/O communication function.
	ISRXD1, ISRXD2	I	VCC1/ VCC2(1)	
	ISTXD0	O	VCC1	Data output pins for the intelligent I/O communication function. (ISTXD2 assigned to port 7_0 is N-channel open drain output.)
	ISTXD1, ISTXD2	O	VCC1/ VCC2(1)	
	IEIN	I	VCC1/ VCC2(1)	Data input pin for the intelligent I/O communication function.
	IEOUT	O	VCC1/ VCC2(1)	Data output pin for the intelligent I/O communication function. (IEOUT assigned to port 7_0 is N-channel open drain output.)
Reference voltage input	VREF	I	–	The VREF pin supplies the reference voltage to the A/D converter and D/A converter.
A/D converter	AN_0 to AN_7	I	VCC1	Analog input pins for the A/D converter.
	AN0_0 to AN0_7, AN2_0 to AN2_7	I	VCC2	
	$\overline{\text{ADTRG}}$	I	VCC1	External trigger input pin for the A/D converter.
	ANEX0	I/O	VCC1	Extended analog input pin for the A/D converter or output pin in external op-amp connection mode.
	ANEX1	I	VCC1	Extended analog input pin for the A/D converter.
D/A converter	DA0, DA1	O	VCC1	Output pins for the D/A converter.
Real-time port	RTP0_0 to RTP0_3 RTP1_0 to RTP1_3 RTP2_0 to RTP2_3 RTP3_0 to RTP3_3	O	VCC1	These pins function as real-time ports. (RTP0_2 and RTP0_3 are N-channel open drain output.)

I: Input O: Output I/O: Input and output

NOTE:

1. Only VCC1 can be used in the 100-pin package.

Table 1.18 Pin Functions (100-Pin and 144-Pin Package) (4/4)

Type	Symbol	I/O Type	Supply Voltage	Description
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7	I/O	VCC2	8-bit CMOS I/O ports. The Port Pi Direction Register (i = 0 to 15) determines if each pin is used as an input port or an output port. The Pull-Up Control Registers determine if the input ports, divided into groups of four, are pulled up or not.
	P6_0 to P6_7, P7_0 to P7_7, P9_0 to P9_7, P10_0 to P10_7	I/O	VCC1	These 8-bit I/O ports are functionally equivalent to P0. (P7_0 and P7_1 are N-channel open drain output.)
	P8_0 to P8_4 P8_6, P8_7	I/O	VCC1	These I/O ports are functionally equivalent to P0.
Input port	P8_5	I	VCC1	Shares the pin with $\overline{\text{NMI}}$. Input port to read $\overline{\text{NMI}}$ pin level.
Key input interrupt input	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	VCC1	Key input interrupt input pins.

I: Input O: Output I/O: Input and output

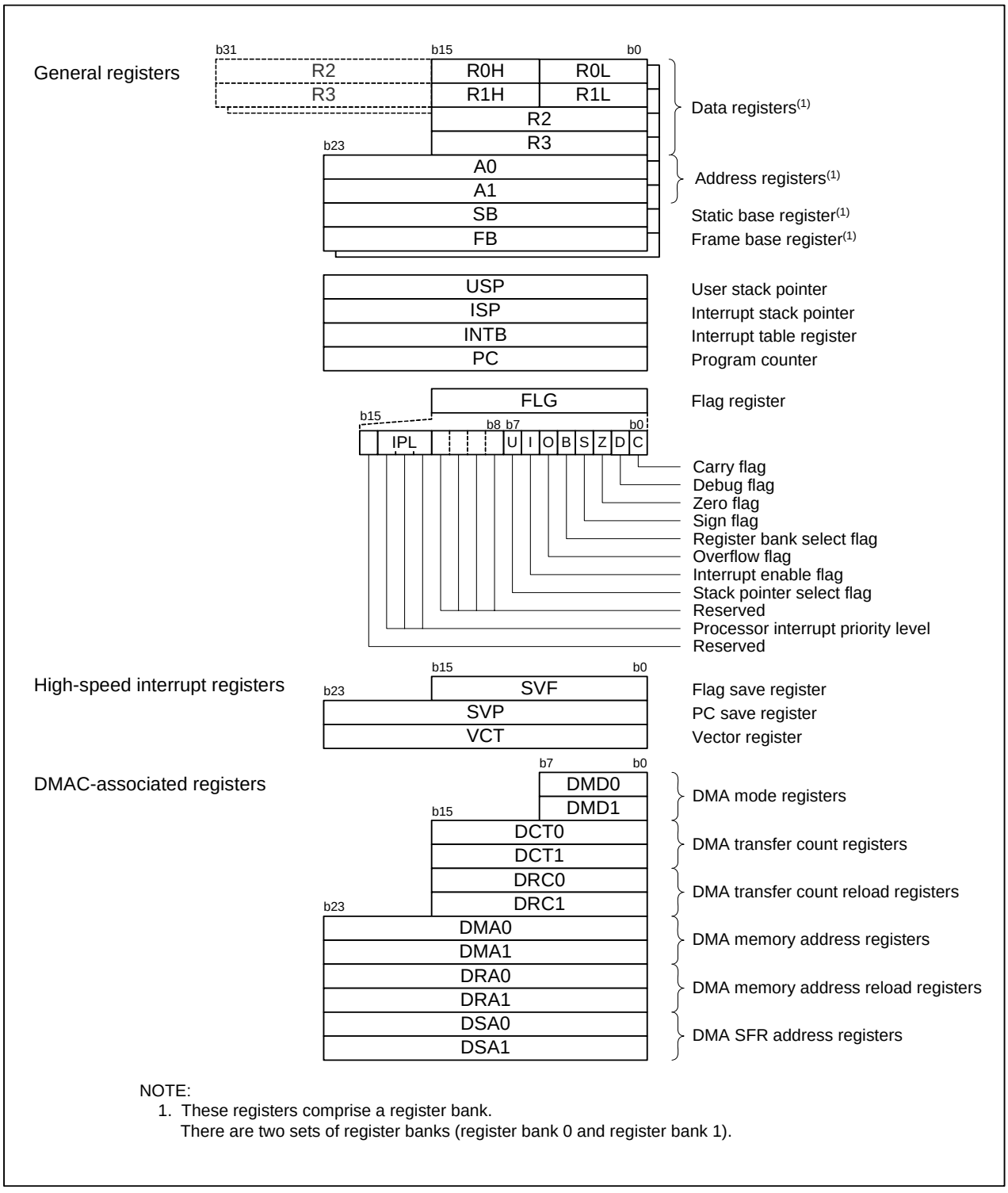
Table 1.19 Pin Functions (144-Pin Package Only)

Type	Symbol	I/O Type	Supply Voltage	Description
$\overline{\text{INT}}$ Interrupt Input	$\overline{\text{INT6}}$ to $\overline{\text{INT8}}$	I	VCC1	$\overline{\text{INT}}$ interrupt input pins.
Serial interface	$\overline{\text{CTS6}}$	I	VCC1/ VCC2	Input pin to control data transmission.
	$\overline{\text{RTS6}}$	O	VCC1/ VCC2	Output pin to control data reception.
	CLK6	I/O	VCC1/ VCC2	Serial clock input/output pin.
	RXD6	I	VCC1/ VCC2	Serial data input pin.
	TXD6	O	VCC1/ VCC2	Serial data output pin.
Intelligent I/O	OUTC2_3 to OUTC2_7	O	VCC2	Output pins for the waveform generation function.
A/D converter	AN15_0 to AN15_7	I	VCC1	Analog input pins for the A/D converter.
I/O port	P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7	I/O	VCC2	These I/O ports are functionally equivalent to P0.
	P14_0 to P14_6, P15_0 to P15_7	I/O	VCC1	These I/O ports are functionally equivalent to P0.

I: Input O: Output I/O: Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers.
The register bank is comprised of eight registers (R0, R1, R2, R3, A0, A1, SB, and FB) out of 28 CPU registers. There are two sets of register banks.



NOTE:
1. These registers comprise a register bank.
There are two sets of register banks (register bank 0 and register bank 1).

Figure 2.1 CPU Register

2.1 General Registers

2.1.1 Data Registers (R0, R1, R2, and R3)

R0, R1, R2, and R3 are 16-bit registers for transfer, arithmetic and logic operations. R0 and R1 can be split into high-order (R0H/R1H) and low-order bits (R0L/R1L) to be used separately as 8-bit data registers.
R0 can be combined with R2 and used as a 32-bit data register (R2R0). The same applies to R3R1.

2.1.2 Address Registers (A0 and A1)

A0 and A1 are 24-bit registers used for A0-/A1-indirect addressing, A0-/A1-relative addressing, transfer, arithmetic and logic operations.

2.1.3 Static Base Register (SB)

SB is a 24-bit register used for SB-relative addressing.

2.1.4 Frame Base Register (FB)

FB is a 24-bit register used for FB-relative addressing.

2.1.5 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are 24 bits wide each. The U flag is used to switch between USP and ISP. Refer to **2.1.8 Flag Register (FLG)** for details on the U flag. Set USP and ISP to even addresses to execute an interrupt sequence efficiently.

2.1.6 Interrupt Table Register (INTB)

INTB is a 24-bit register indicating the starting address of a relocatable interrupt vector table.

2.1.7 Program Counter (PC)

PC is 24 bits wide and indicates the address of the next instruction to be executed.

2.1.8 Flag Register (FLG)

FLG is a 16-bit register indicating the CPU state.

2.1.8.1 Carry Flag (C)

The C flag indicates whether or not carry or borrow has been generated after executing an instruction.

2.1.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.1.8.3 Zero Flag (Z)

The Z flag becomes 1 when an arithmetic operation results in 0; otherwise becomes 0.

2.1.8.4 Sign Flag (S)

The S flag becomes 1 when an arithmetic operation results in a negative value; otherwise becomes 0.

2.1.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is set to 0. Register bank 1 is selected when this flag is set to 1.

2.1.8.6 Overflow Flag (O)

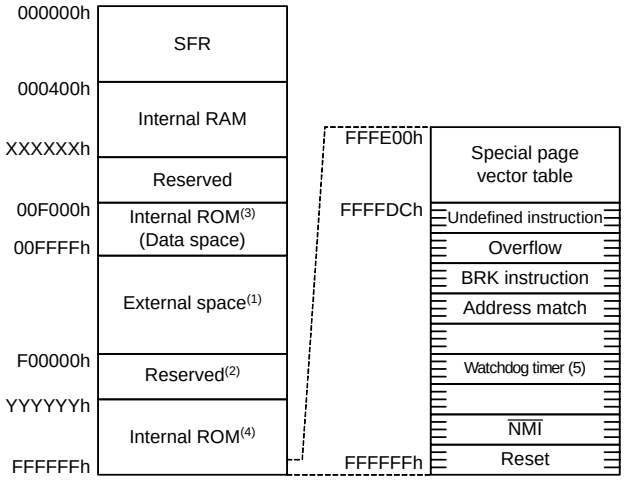
The O flag becomes 1 when an arithmetic operation results in an overflow; otherwise becomes 0.

3. Memory

Figure 3.1 shows a memory map of the M32C/87 Group (M32C/87, M32C/87A, M32C/87B).
The M32C/87 Group (M32C/87, M32C/87A, M32C/87B) has 16-Mbyte address space from addresses 000000h to FFFFFFh.
The internal ROM is allocated in lower addresses, beginning with address FFFFFFh. For example, a 512-Kbyte internal ROM area is allocated in addresses F80000h to FFFFFFh.
The fixed interrupt vectors are allocated in addresses FFFFDCh to FFFFFFh. They store the starting address of each interrupt routine.
The internal RAM is allocated higher addresses, beginning with address 000400h. For example, a 48-Kbyte internal RAM area is allocated in addresses 000400h to 00C3FFh. The internal RAM is used not only for storing data but for the stacks when subroutines are called or when interrupt requests are acknowledged.
SFRs are allocated in addresses 000000h to 0003FFh. The peripheral function control registers such as for I/O ports, A/D converters, serial interfaces, timers are allocated here. All blank spaces within SFRs are reserved and cannot be accessed by users.
The special page vectors are allocated addresses FFFE00h to FFFFDBh. They are used for the JMPS instruction and JSRS instruction. Refer to the Renesas publication **M32C/80 Series Software Manual** for details.

Internal RAM	
Capacity	XXXXXXh
24 Kbytes	0063FFh
31 Kbytes	007FFFh
48 Kbytes	00C3FFh

Internal ROM	
Capacity	YYYYYYh
384 Kbytes	FA0000h
512 Kbytes	F80000h
768 Kbytes	F40000h
1024 Kbytes	F00000h



NOTES:
1. The space is used as the external space in memory expansion mode and in microprocessor mode. It is reserved in single-ship mode.
2. The space is reserved in memory expansion mode. It is used as the external space in microprocessor mode.
3. Additional 4-Kbyte space is provided in the flash memory version to store data. This space is used in single-chip mode and memory expansion mode. It is reserved in microprocessor mode.
4. This space is used in single-chip mode and memory expansion mode. It is used as the external space in microprocessor mode.
5. The watchdog timer interrupt, oscillation stop detection interrupt, and Vdet4 detection interrupt use the same vector.

Figure 3.1 Memory Map

Table 4.2 SFR Address Map (2/20)

Address	Register	Symbol	After Reset
0030h			
0031h			
0032h			
0033h			
0034h			
0035h			
0036h			
0037h			
0038h	Address Match Interrupt Register 6	RMAD6	000000h
0039h			
003Ah			
003Bh			
003Ch	Address Match Interrupt Register 7	RMAD7	000000h
003Dh			
003Eh			
003Fh			
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h	External Space Wait Control Register 0	EWCR0	X0X0 0011b
0049h	External Space Wait Control Register 1	EWCR1	X0X0 0011b
004Ah	External Space Wait Control Register 2	EWCR2	X0X0 0011b
004Bh	External Space Wait Control Register 3	EWCR3	X0X0 0011b
004Ch			
004Dh			
004Eh			
004Fh			
0050h			
0051h			
0052h			
0053h			
0054h			
0055h	Flash Memory Control Register 1	FMR1	0000 0X0Xb
0056h			
0057h	Flash Memory Control Register 0	FMR0	0000 0001b(Flash Memory) XXXX XXX0b(Mask ROM)
0058h			
0059h			
005Ah			
005Bh			
005Ch			
005Dh			
005Eh			
005Fh			

X: Undefined
Blank spaces are all reserved. No access is allowed.

Table 5.3 Recommended Operating Conditions (2/3)
(VCC1 = VCC2 = 3.0 to 5.5 V, Topr = -20 to 85°C unless otherwise specified

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
IOH(peak)	Peak output high “H” current(2)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(3)			-10.0	mA
IOH(avg)	Average output high “H” current(1)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(3)			-5.0	mA
IOL(peak)	Peak output low “L” current(2)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(3)			10.0	mA
IOL(avg)	Average output low “L” current(1)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(3)			5.0	mA

NOTES:
1. Average output current is the average value within 100 ms.
2. A total IOL(peak) of P0, P1, P2, P8_6, P8_7, P9, P10, P11, P14, and P15 must be 80 mA or less.
   A total IOL(peak) of P3, P4, P5, P6, P7,P8_0 to P8_4, P12, and P13 must be 80 mA or less.
   A total IOH(peak) of P0, P1, P2, and P11 must be -40 mA or less.
   A total IOH(peak) of P8_6 to P8_7, P9, P10, P14, and P15 must be -40 mA or less.
   A total IOH(peak) of P3, P4, P5, P12, and P13 must be -40 mA or less.
   A total IOH(peak) of P6, P7, and P8_0 to P8_4 must be -40 mA or less.
3. P11 to P15 are provided in the 144-pin package only.

VCC1 = VCC2 = 5V

Table 5.5 Electrical Characteristics (1/3)
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C, f(CPU) = 32 MHz unless otherwise specified)

Symbol	Parameter		Measurement Condition	Standard			Unit
				Min.	Typ.	Max.	
VOH	Output high “H” voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(1)	IOH = -5 mA	VCC2 - 2.0		VCC2	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P14_0 to P14_6, P15_0 to P15_7(1)	IOH = -5 mA	VCC1 - 2.0		VCC1	
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7 P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(1)	IOH = -200 µA	VCC2 - 0.3		VCC2	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P14_0 to P14_6, P15_0 to P15_7(1)	IOH = -200 µA	VCC1 - 0.3		VCC1	
		XOUT	IOH = -1 mA	3.0		VCC1	V
		XCOUT Drive capability = high	No load applied		2.5		V
		XCOUT Drive capability = low	No load applied		1.6		V
VOL	Output low “L” voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(1)	IOL = 5 mA			2.0	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(1)	IOL = 200 µA			0.45	V
		XOUT	IOL = 1 mA			2.0	V
		XCOUT Drive capability = high	No load applied		0		V
		XCOUT Drive capability = low	No load applied		0		V
VT+ - VT-	Hysteresis	$\overline{HOLD}$, $\overline{RDY}$, TA0IN to TA4IN, $\overline{TB0IN}$ to $\overline{TB5IN}$, $\overline{INT0}$ to $\overline{INT8}$, $\overline{ADTRG}$, $\overline{CTS0}$ to $\overline{CTS6}$, CLK0 to $\overline{CLK6}$, TA0OUT to TA4OUT, $\overline{NMI}$, $\overline{KI0}$ to $\overline{KI3}$, RXD0 to RXD6, SCL0 to SCL4, SDA0 to SDA4, INPC1_0 to INPC1_7, ISCLK0 to ISCLK2, ISRXD0 to ISRXD2, IEIN, CAN0IN, CAN1IN, $\overline{CAN1WU}$		0.2		1.0	V
		$\overline{RESET}$		0.2		1.8	V

NOTE:
1. P11 to P15 are provided in the 144-pin package only.

VCC1 = VCC2 = 5V

Table 5.6 Electrical Characteristics (2/3)
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C, f(CPU) = 32 MHz unless otherwise specified)

Symbol	Parameter		Measurement Condition	Standard			Unit
				Min.	Typ.	Max.	
IIH	Input high "H" current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(1), XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	VI = 5 V			5.0	µA
IIL	Input low "L" current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(1), XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	VI = 0V			-5.0	µA
RPULLUP	Pull-up resistance	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(1)	VI = 0V	30	50	167	kΩ
RfXIN	Feedback resistance	XIN			1.5		MΩ
RfXCIN	Feedback resistance	XCIN			10		MΩ
VRAM	RAM data retention voltage	In stop mode		2.0			V

NOTE:
1. P11 to P15 are provided in the 144-pin package only.

VCC1 = VCC2 = 5V

Timing Requirements
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.27 External Interrupt $\overline{INTi}$ Input (Edge Sensitive)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tw(INH)	$\overline{INTi}$ input high (“H”) pulse width	250		ns
tw(INL)	$\overline{INTi}$ input low (“L”) pulse width	250		ns

i = 0 to 8(1)

NOTE:
1. $\overline{INT6}$ to $\overline{INT8}$ are provided in the 144-pin package only.

VCC1 = VCC2 = 5V

Switching Characteristics
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.30 Memory Expansion Mode and Microprocessor Mode (when accessing external memory space with multiplexed bus)

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min.	Max.	
td(BCLK-AD)	Address output delay time	See Figure 5.2		18	ns
th(BCLK-AD)	Address output hold time (BCLK standard)		-3		ns
th(RD-AD)	Address output hold time (RD standard)(5)		(note 1)		ns
th(WR-AD)	Address output hold time (WR standard)(5)		(note 1)		ns
td(BCLK-CS)	Chip-select signal output delay time			18	ns
th(BCLK-CS)	Chip-select signal output hold time (BCLK standard)		-3		ns
th(RD-CS)	Chip-select signal output hold time (RD standard)(5)		(note 1)		ns
th(WR-CS)	Chip-select signal output hold time (WR standard)(5)		(note 1)		ns
td(BCLK-RD)	RD signal output delay time			18	ns
th(BCLK-RD)	RD signal output hold time		-5		ns
td(BCLK-WR)	WR signal output delay time			18	ns
th(BCLK-WR)	WR signal output hold time		-5		ns
td(DB-WR)	Data output delay time (WR standard)		(note 2)		ns
th(WR-DB)	Data output hold time (WR standard)(5)		(note 1)		ns
td(BCLK-ALE)	ALE signal output delay time (BCLK standard)			18	ns
th(BCLK-ALE)	ALE signal output hold time (BCLK standard)		-2		ns
td(AD-ALE)	ALE signal output delay time (address standard)		(note 3)		ns
th(ALE-AD)	ALE signal output hold time (address standard)		(note 4)		ns
tdz(RD-AD)	Address output float start time			8	ns

NOTES:

1. Values, which depend on BCLK frequency, can be obtained from the following equations.

$$th(RD\text{-}AD) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(WR\text{-}AD) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(RD\text{-}CS) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(WR\text{-}CS) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(WR\text{-}DB) = \frac{10^9}{f(BCLK) \times 2} - 15\ [ns]$$

2. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equation.

$$td(DB\text{-}WR) = \frac{10^9 \times m}{f(BCLK) \times 2} - 25\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $m = (b \times 2) - 1$)

3. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equation.

$$td(AD\text{-}ALE) = \frac{10^9 \times n}{f(BCLK) \times 2} - 20\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $n = a$)

4. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equation.

$$th(ALE\text{-}AD) = \frac{10^9 \times n}{f(BCLK) \times 2} - 20\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $n = a$)

5. tc [ns] is added when recovery cycle is inserted.

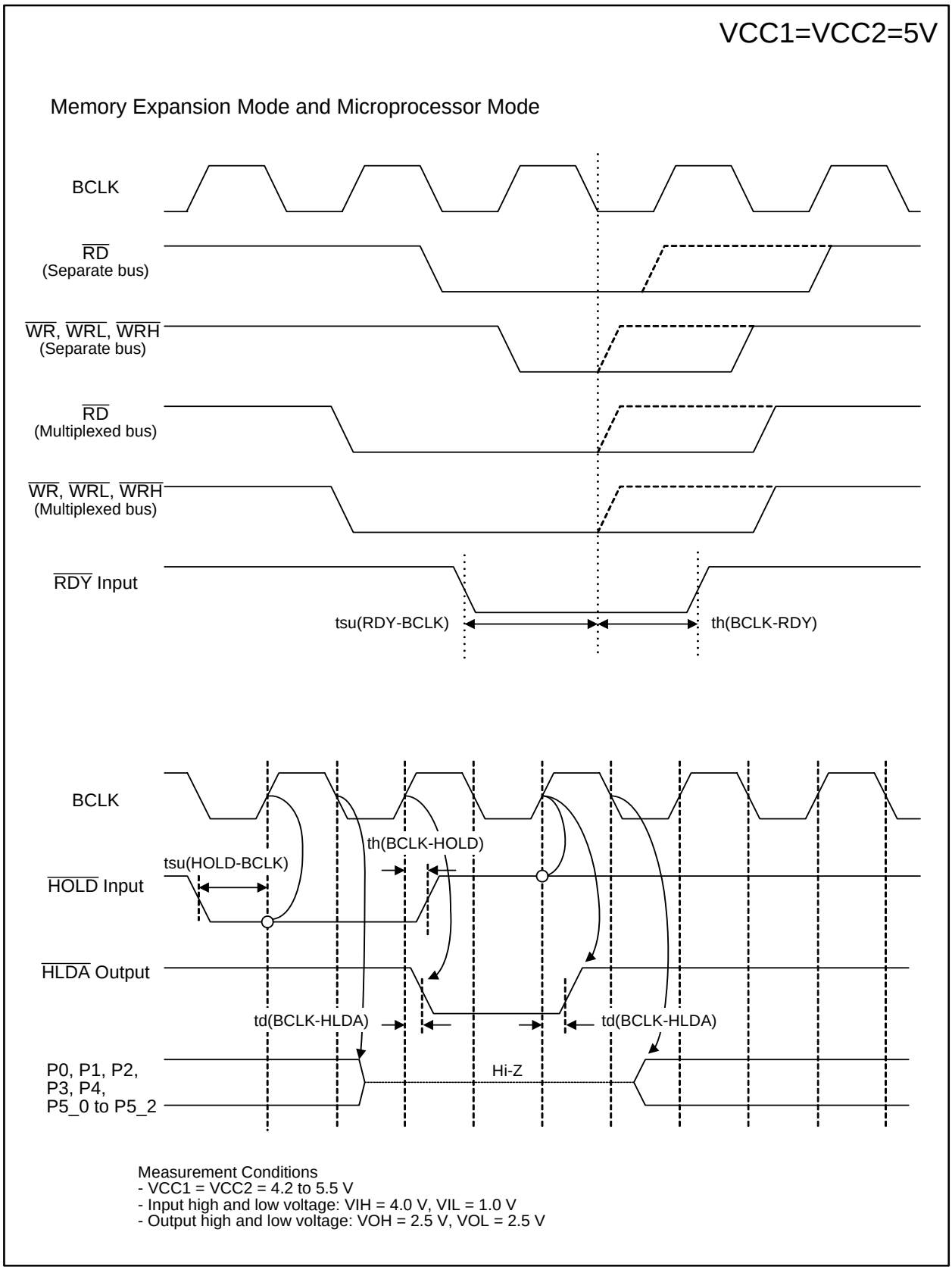
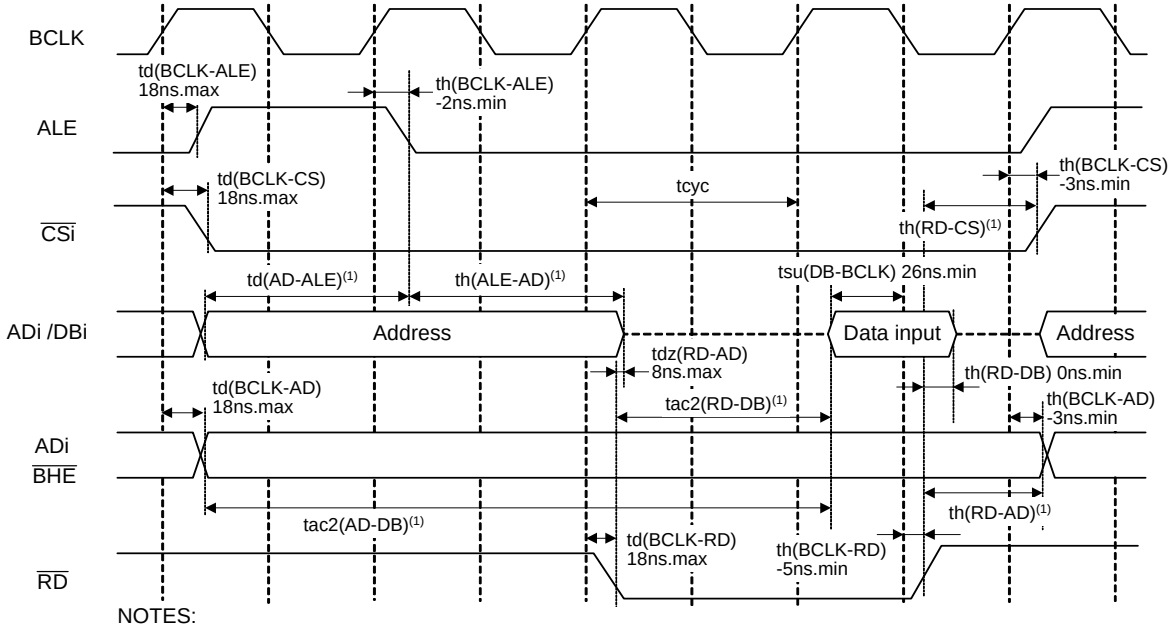


Figure 5.4 VCC1 = VCC2 = 5 V Timing Diagram (2/4)

Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space with the multiplexed bus)

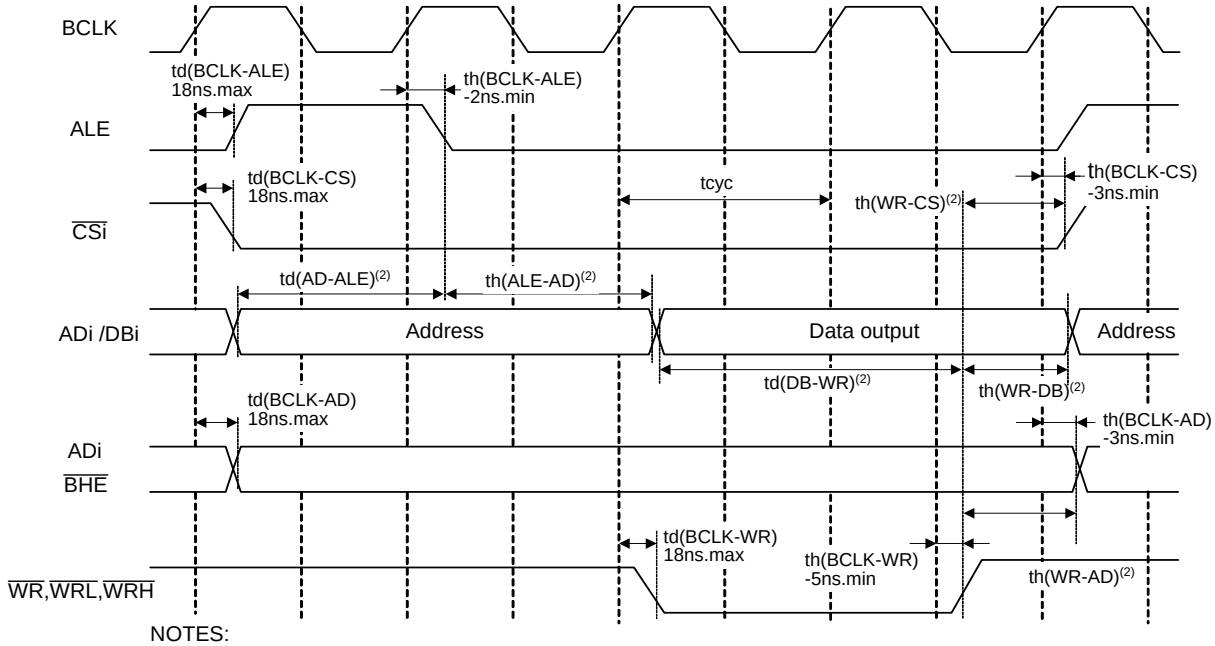
VCC1=VCC2=5V

Read Timing (2φ + 2φ Bus Cycle)



NOTES:
1. Varies with operation frequency:
td(AD-ALE) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(ALE-AD) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(RD-AD) = (tcyc / 2 - 10) ns.min, th(RD-CS) = (tcyc / 2 - 10) ns.min
tac2(RD-DB) = (tcyc / 2 x m - 35) ns.max (if external bus cycle aφ + bφ, m = (b x 2) - 1)
tac2(AD-DB) = (tcyc / 2 x p - 35) ns.max (if external bus cycle aφ + bφ, p = {(a + b - 1) x 2} + 1)

Write Timing (2φ + 2φ Bus Cycle)



NOTES:
1. Varies with operation frequency:
td(AD-ALE) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(ALE-AD) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(WR-AD) = (tcyc / 2 - 10) ns.min, th(WR-CS) = (tcyc / 2 - 10) ns.min
th(WR-DB) = (tcyc / 2 - 15) ns.min
td(DB-WR) = (tcyc / 2 x m - 25) ns.min (if external bus cycle aφ + bφ, m = (b x 2) - 1)

$$tcyc = \frac{10^9}{f(BCLK)}$$

Measurement Conditions:
- VCC1 = VCC2 = 4.2 to 5.5 V
- Input high and low voltage VIH = 2.5 V, VIL = 0.8 V
- Output high and low voltage VOH = 2.0 V, VOL = 0.8 V

Figure 5.6 VCC1 = VCC2 = 5 V Timing Diagram (4/4)

VCC1 = VCC2 = 3.3 V

Table 5.33 Electrical Characteristics (3/3)
(VCC1 = VCC2 = 3.3 V, VSS = 0 V, Topr = 25°C)

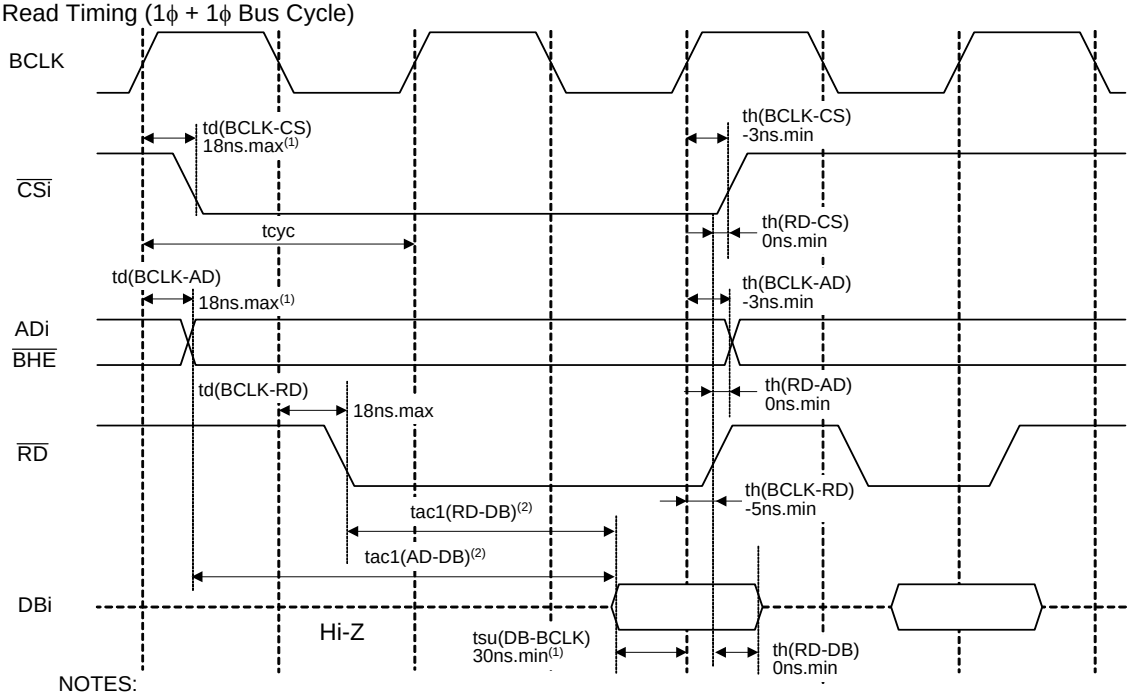
Symbol	Parameter	Measurement Condition(1)		Standard			Unit
				Min.	Typ.	Max.	
ICC	Power supply current	Flash memory version	f(CPU) = 24 MHz		23	33	mA
			f(CPU) = 16 MHz		17		mA
			f(CPU) = 8 MHz		11		mA
			f(CPU) = f(Ring) In on-chip oscillator low-power consumption mode		2.6		mA
			f(CPU) = 32 kHz In low-power consumption mode While flash memory is operating		430		µA
			f(CPU) = 32 kHz In low-power consumption mode While flash memory is stopped(2)		30		µA
			Wait mode: f(CPU) = f(Ring) After entering wait mode from on-chip oscillator low-power consumption mode		45		µA
			Stop mode (while clock is stopped)		0.8	5	µA
			Stop mode (while clock is stopped) Topr = 85°C			50	µA
		Mask ROM version	f(CPU) = 24 MHz		23	33	mA
			f(CPU) = 16 MHz		17		mA
			f(CPU) = 8 MHz		11		mA
			f(CPU) = f(Ring) In on-chip oscillator low-power consumption mode		1		mA
			f(CPU) = 32 kHz In low-power consumption mode		30		µA
			Wait mode: f(CPU) = f(Ring) After entering wait mode from on-chip oscillator low-power consumption mode		45		µA
			Stop mode (while clock is stopped)		0.8	5	µA
			Stop mode (while clock is stopped) Topr = 85°C			50	µA

NOTES:
1. In single-chip mode, leave the output pins open and connect the input pins to VSS.
2. Value is obtained when setting the FMSTP bit in the FMR0 register to 1 (flash memory stopped) and running the program on RAM.

Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space)

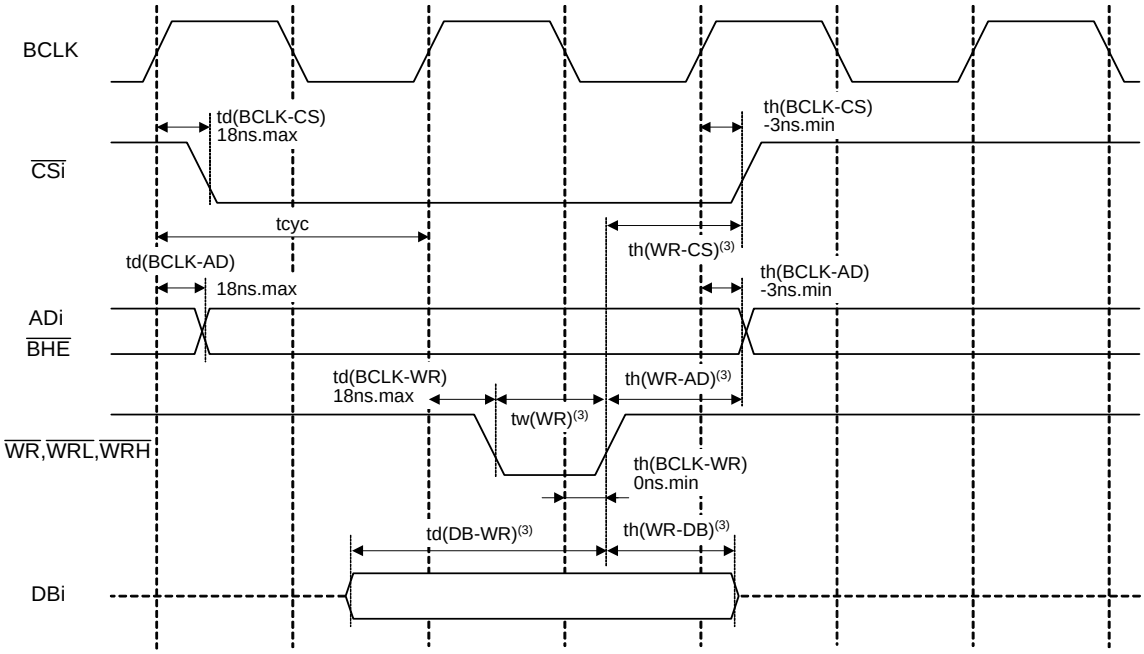
VCC1=VCC2=3.3V

Read Timing (1ϕ + 1ϕ Bus Cycle)



NOTES:
1. Values guaranteed only when the MCU is used stand-alone.
   A maximum of 35 ns is guaranteed for td(BCLK-AD) + tsu(DB-BCLK).
2. Varies with operation frequency:
   tac1(RD-DB) = (tcyc / 2 x m - 35) ns.max (if external bus cycle aϕ + bϕ, m = (b x 2) + 1)
   tac1(AD-DB) = (tcyc x n - 35) ns.max (if external bus cycle aϕ + bϕ, n = a + b)

Write Timing (1ϕ + 1ϕ Bus Cycle)



NOTES:
3. Varies with operation frequency:
   td(DB-WR) = (tcyc x m - 20) ns.min
   (if external bus cycle aϕ + bϕ, m = b)
   th(WR-DB) = (tcyc / 2 - 20) ns.min
   th(WR-AD) = (tcyc / 2 - 15) ns.min
   th(WR-CS) = (tcyc / 2 - 10) ns.min
   tw(WR) = (tcyc / 2 x n - 15) ns.min
   (if external bus cycle aϕ + bϕ, n = (b x 2) - 1)

Measurement Conditions:
- VCC1 = VCC2 = 3.0 to 3.6 V
- Input high and low voltage: VIH = 1.5 V, VIL = 0.5 V
- Output high and low voltage: VOH = 1.5 V, VOL = 1.5 V

$$tcyc = \frac{10^9}{f(BCLK)}$$

Figure 5.9 VCC1 = VCC2 = 3.3 V Timing Diagram (3/4)

REVISION HISTORY	M32C/87 Group Datasheet

Rev.	Date	Description	
		Page	Summary
		46	**Special Function Registers (SFRs)** • **Table 4.20** A value of After Reset column in 03FFh modified